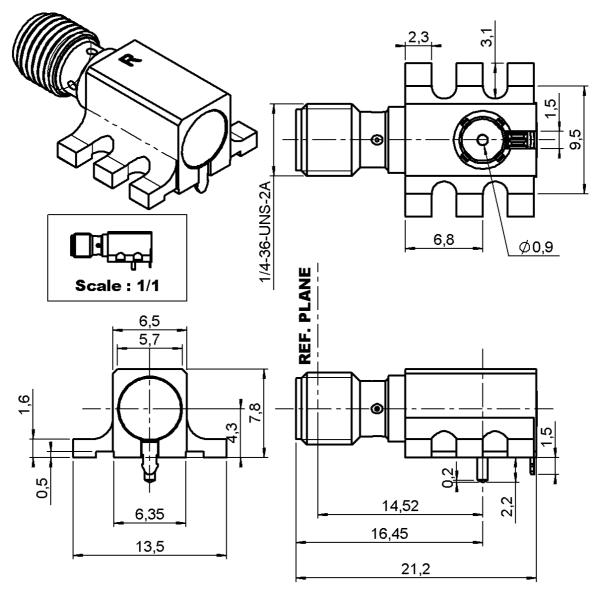
REEL PACKAGING PER 250

R124.682.820

Series : **SMA-COM**



All dimensions are in mm.

COMPONENTS	MATERIALS	PLATINGS (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS -	BRASS BERYLLIUM COPPER - PTFE - BRASS -	GBR 2 GOLD 1.3 OVER COPPER 2.5 - GOLD 0.2 OVER COPPER 2

Issue: 0738 D

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



REEL PACKAGING PER 250

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Series: **SMA-COM**

PACKAGING

Standard	Unit	Other
250	'W' option	Contact us

SPECIFICATION

1301-RNT 403 054 / 003 Rev. D

ELECTRICAL CHARACTERISTICS

Impedance **50** Ω Frequency **0-18** GHz

VSWR

0,0000 x F(GHz) Maxi Insertion loss **0.07** $\sqrt{F(GHz)}$ dB Maxi RF leakage **90** - F(GHz)) dB mini

Voltage rating 350 Veff Maxi Dielectric withstanding voltage 1000 Veff mini Insulation resistance **5000** MΩ mini

ENVIRONMENTAL

Operating temperature -65/+165 ° C

NA Atm.cm3/s Hermetic seal

Panel leakage NA

OTHERS CHARACTERISTICS

Assembly instruction

Others:

Coaxial transmission line only

1.15 to 2GHz

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end 27 N mini Axial force – Opposite end 27 N mini Torque NA N.cm mini

Recommended torque

Mating **60** N.cm Panel nut NA N.cm

Mating life 100 Cycles mini

Weight **5,5610** g

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REEL PACKAGING PER 250

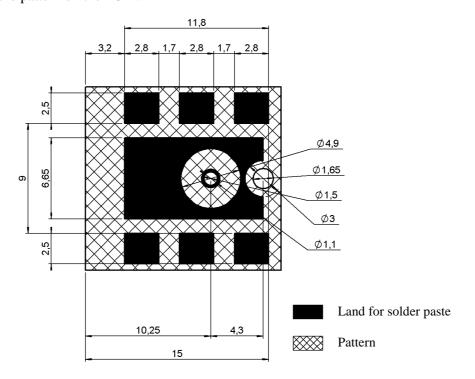
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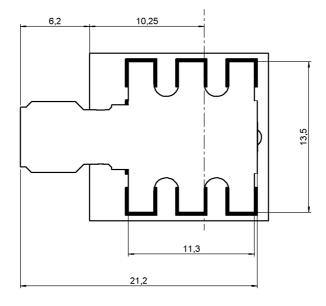
SMA SERIES - INFORMATION

Coplanar line : pattern and signal are on the same side . Thickness of PCB : .063(1.6mm) The material of PCB is the epoxy resin of glass fabrics bacs . (Er = 4.8) . The solder resist should be printed

exept for the land pattern on the PCB.



SHADOW OF SMA RECEPTACLE FOR VIDEO CAMERA



Issue: 0738 D

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RADIALL®

RIGHT ANGLE SMT RECEPTACLE REEL PACKAGING PER 250

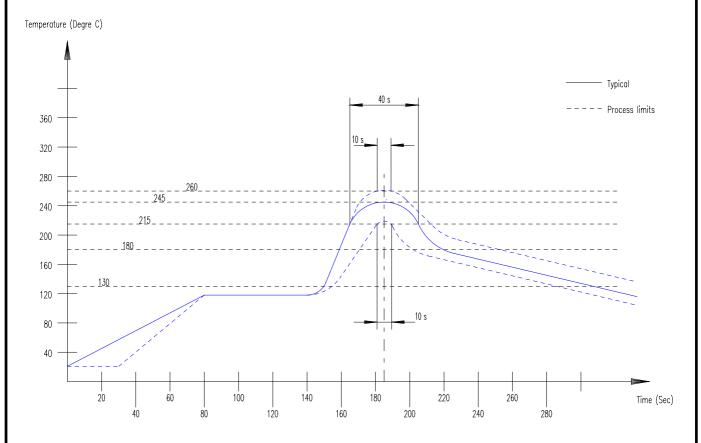
R124.682.820

Series: SMA-COM

SOLDER PROCEDURE

- 1. Deposit solder paste 'SN62RP11AGS90' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. Video camera is prefered to check the positioning of the compnent. Adhesive agents are forbidden on the receptacle.
- 3. Soldering by infra-red reflow.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFIL



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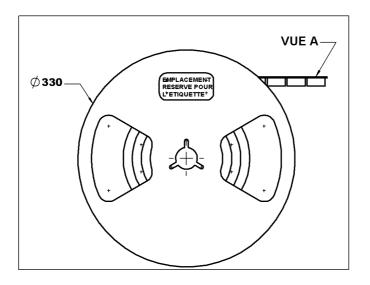
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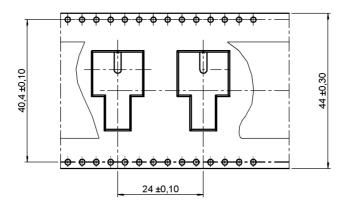
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bobine Ech: 0.7



Vue A (ech : 1.5) sans connecteurs

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